



Part Number : [1703050118](#)

Product Description : EdgeLine CoPlanar+ ESP Connector, 15 Gbps, 0.80mm Pitch, 2.36mm PCB Thickness, 118 Circuits, 30.0A Power Module

Series Number : 170305

Status : Active

Product Category : Card Edge Connectors

Documents & Resources

Drawings

[Drawing 1703050118_sd.pdf](#)

[Packaging Design Drawing PK-170305-0001-001.pdf](#)

3D Models and Design Files

[3D Model 1703050118_stp.zip](#)

[Electrical Model Document EE-170082-0001-001.pdf](#)

[S-Parameter Model SP-170082-0001-001.zip](#)

[Symbol Footprint Data SYM-170305-0118-001.zip](#)

Specifications

[Application Specification AS-170305-0001-001.pdf](#)


[Application Specification AS-170305-0002-001.pdf](#)

[Product Specification PS-170305-0001-001.pdf](#)

[Test Summary TS-170305-0001-001.pdf](#)

Product Environment Compliance

Compliance

GADSL/IMDS	Not Relevant
China RoHS	
EU ELV	Not Relevant
Low-Halogen Status	Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2024)4144-DC (27 June 2024)
EU RoHS	Compliant per EU 2015/863

Multiple Part Product Compliance Statements

- Eu RoHS
- REACH SVHC
- Low-Halogen

Multiple Part Industry Compliance Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

EU RoHS Certificate of Compliance

Part Details

General

Status	Active
Category	Card Edge Connectors
Series	170305
Description	EdgeLine CoPlanar+ ESP Connector, 15 Gbps, 0.80mm Pitch, 2.36mm PCB Thickness, 118 Circuits, 30.0A Power Module
Component Type	Edgecard to PCB
Product Family	EdgeLine High-Speed Connectors
Product Name	EdgeLine
Standard Based	General
UPC	887191168760

Agency

UL	E29179
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Electrical

Current - Maximum per Contact	0.5A
Data Rate	12.5-20.0 Gbps
High Power Bay (30.0A or more)	No
Voltage - Maximum	250V AC (RMS)/DC

Physical

Circuit Size Range	65-200 Circuits
Circuits (Loaded)	118
Circuits (maximum)	118
Color - Resin	Black

Durability (mating cycles max)	200
Edge Card Thickness	2.36mm
Entry Angle	N/A
Keying to Mating Part	N/A
Material - Metal	Copper Alloy
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	23.600/g
Orientation	Coplanar
Packaging Type	Tray
PCB Locator	No
PCB Thickness - Recommended	2.79mm
Pitch - Mating Interface	2.35mm
Pitch - Termination Interface	0.80mm
Plating min - Mating	0.762μm
Plating min - Termination	0.762μm
Polarized to Mating Part	Yes
(p)ower-(s)ignal Configuration	118s - 0p
Temperature Range - Operating	-40° to +105°C
Termination Interface Style	Through Hole - Compliant Pin

Solder Process Data

Lead-Free Process Capability	N/A
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